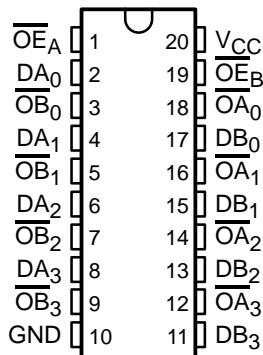


- Function and Pinout Compatible With FCT and F Logic
- 25- Ω Output Series Resistors Reduce Transmission-Line Reflection Noise
- TTL-Output-Level Version of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Fully Compatible With TTL Input and Output Logic Levels
- 12-mA Output Sink Current
15-mA Output Source Current
- 3-State Outputs

**Q OR SO PACKAGE
(TOP VIEW)**



description

The CY74FCT2240T is an octal buffer and line driver that includes on-chip 25- Ω terminating resistors at each of the outputs to minimize noise resulting from reflections or standing waves in high-performance applications. The on-chip resistors reduce overall board space and component count. Designed to be employed as a memory address driver, clock driver, and bus-oriented transmitter/receiver, this device provides speed and drive capabilities commensurate with its fastest bipolar logic counterparts, while reducing power dissipation. The input and output voltage levels allow direct interface with TTL, NMOS, and CMOS devices, without the need for external components.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T _A	PACKAGE [†]		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QSOP – Q	Tape and reel	4.1	CY74FCT2240CTQCT	FCT2240C
	SOIC – SO	Tube	4.1	CY74FCT2240CTSOC	FCT2240C
		Tape and reel	4.1	CY74FCT2240CTSOCT	
	QSOP – Q	Tape and reel	4.8	CY74FCT2240ATQCT	FCT2240A
	SOIC – SO	Tube	8	CY74FCT2240TSOC	FCT2240
		Tape and reel	8	CY74FCT2240TSOCT	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**CY74FCT2240T
8-BIT BUFFER/LINE DRIVER
WITH 3-STATE OUTPUTS**

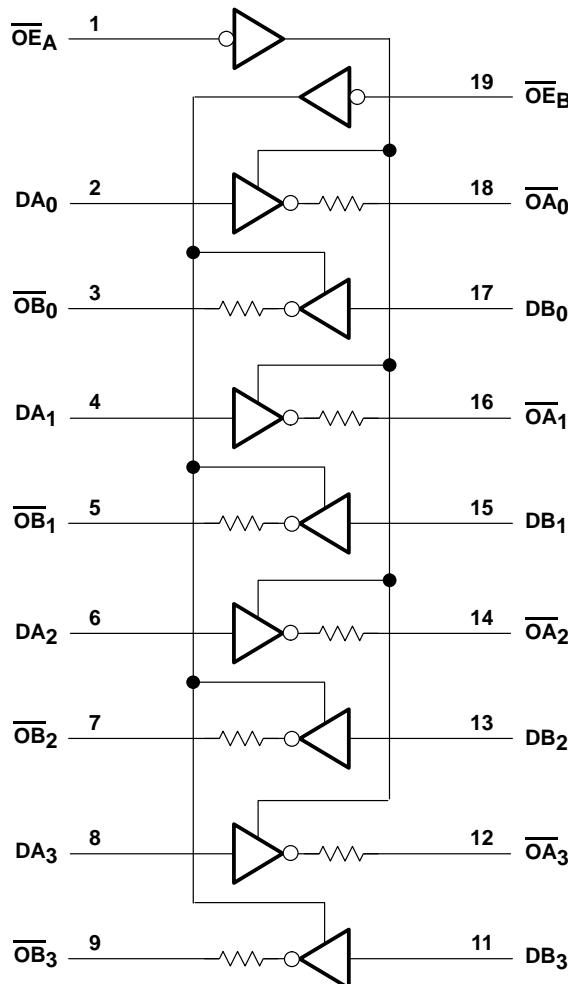
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FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE_A}$	$\overline{OE_B}$	D	\overline{O}
L	L	L	H
L	L	H	L
H	H	X	Z

H = High logic level, L = Low logic level,
X = Don't care, Z = High-impedance (off)
state

logic diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.75	5	5.25	V
V _{IH}	High-level input voltage		2		V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			-15	mA
I _{OL}	Low-level output current			12	mA
T _A	Operating free-air temperature	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

CY74FCT2240T
8-BIT BUFFER/LINE DRIVER
WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYPT [†]	MAX	UNIT
V_{IK}	$V_{CC} = 4.75$ V,	$I_{IN} = -18$ mA		-0.7	-1.2	V
V_{OH}	$V_{CC} = 4.75$ V,	$I_{OH} = -15$ mA	2.4	3.3		V
V_{OL}	$V_{CC} = 4.75$ V,	$I_{OL} = 12$ mA		0.3	0.55	V
R_{OUT}	$V_{CC} = 4.75$ V,	$I_{OL} = 12$ mA	20	25	40	Ω
V_{hys}	All inputs			0.2		V
I_I	$V_{CC} = 5.25$ V,	$V_{IN} = V_{CC}$		5		μA
I_{IH}	$V_{CC} = 5.25$ V,	$V_{IN} = 2.7$ V		± 1		μA
I_{IL}	$V_{CC} = 5.25$ V,	$V_{IN} = 0.5$ V		± 1		μA
I_{OZH}	$V_{CC} = 5.25$ V,	$V_{OUT} = 2.7$ V		10		μA
I_{OZL}	$V_{CC} = 5.25$ V,	$V_{OUT} = 0.5$ V		-10		μA
I_{OS}^{\ddagger}	$V_{CC} = 5.25$ V,	$V_{OUT} = 0$ V	-60	-120	-225	mA
I_{off}	$V_{CC} = 0$ V,	$V_{OUT} = 4.5$ V		± 1		μA
I_{CC}	$V_{CC} = 5.25$ V,	$V_{IN} \leq 0.2$ V,	$V_{IN} \geq V_{CC} - 0.2$ V	0.1	0.2	mA
ΔI_{CC}	$V_{CC} = 5.25$ V, $V_{IN} = 3.4$ V [§] , $f_1 = 0$, Outputs open			0.5	2	mA
$I_{CCD}^{\mathbb{T}}$	$V_{CC} = 5.25$ V, One input switching at 50% duty cycle, Outputs open, $O_{EA} = O_{EB} = GND$, $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V			0.06	0.12	mA/ MHz
$I_C^{\#}$	$V_{CC} = 5.25$ V, Outputs open, $O_{EA} = O_{EB} = GND$	One bit switching at $f_1 = 10$ MHz at 50% duty cycle	$V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V	0.7	1.4	mA
			$V_{IN} = 3.4$ V or GND	1	2.4	
		Eight bits switching at $f_1 = 2.5$ MHz at 50% duty cycle	$V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V	1.3	2.6	
			$V_{IN} = 3.4$ V or GND	3.3	10.6	
C_i				5	10	pF
C_o				9	12	pF

[†] Typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ C$.

[‡] Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

[§] Per TTL-driven input ($V_{IN} = 3.4$ V); all other inputs at V_{CC} or GND

[¶] This parameter is derived for use in total power-supply calculations.

$I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4$ V)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

**CY74FCT2240T
8-BIT BUFFER/LINE DRIVER
WITH 3-STATE OUTPUTS**

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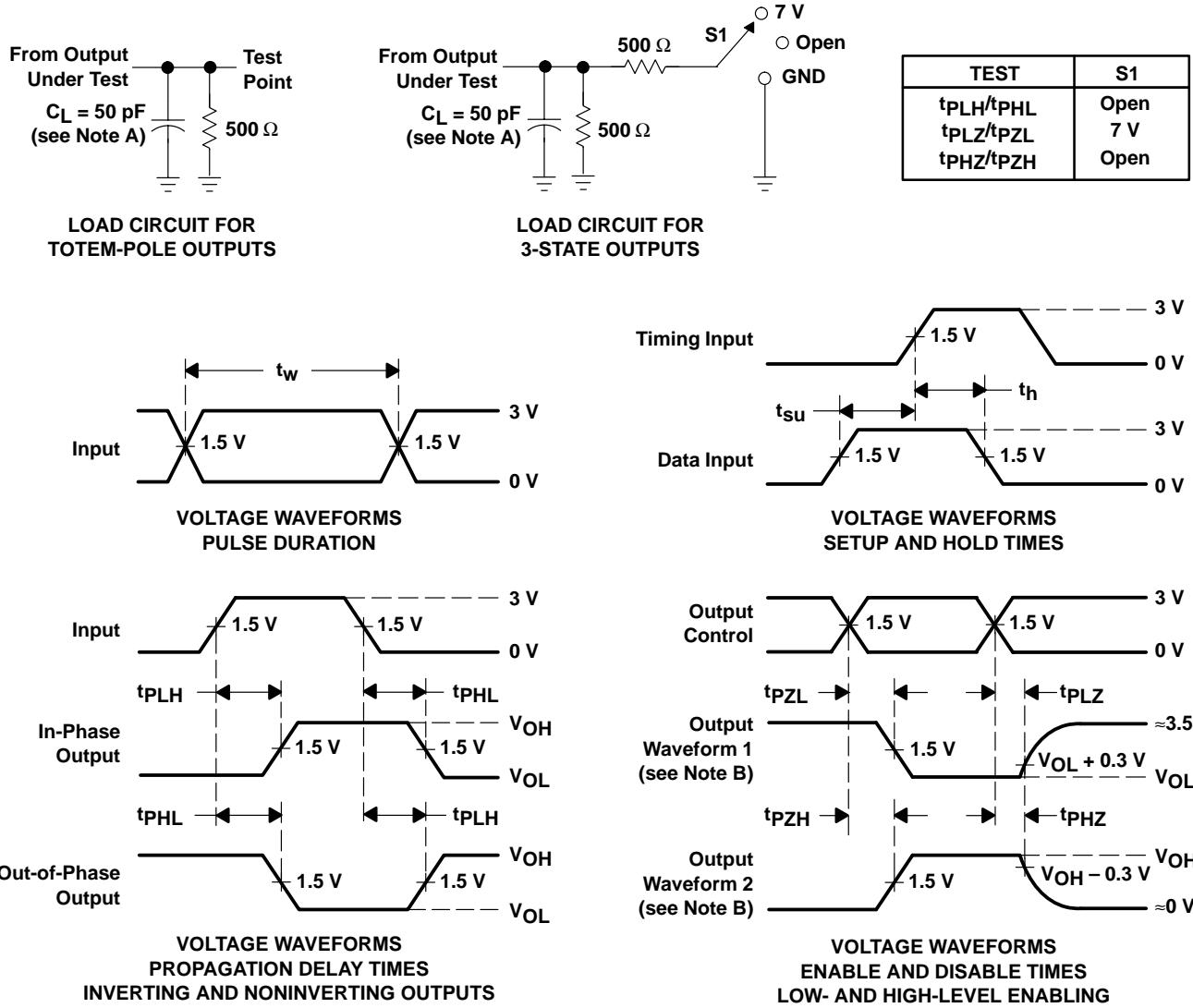
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT2240T		CY74FCT2240AT		CY74FCT2240CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	\bar{O}	1.5	8	1.5	4.8	1.5	4.1	ns
t_{PHL}			1.5	8	1.5	4.8	1.5	4.1	
t_{PZH}	\bar{OE}	\bar{O}	1.5	10	1.5	6.5	1.5	5.8	ns
t_{PZL}			1.5	10	1.5	6.5	1.5	5.8	
t_{PHZ}	\bar{OE}	\bar{O}	1.5	9.5	1.5	5.9	1.5	5.2	ns
t_{PLZ}			1.5	9.5	1.5	5.9	1.5	5.2	

CY74FCT2240T
8-BIT BUFFER/LINE DRIVER
WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74FCT2244CTSOCTE4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		Samples
74FCT2244CTSOCTG4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		Samples
CY74FCT2240CTQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2240C	Samples
CY74FCT2240CTQCTE4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2240C	Samples
CY74FCT2244ATQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2244A	Samples
CY74FCT2244ATQCTE4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2244A	Samples
CY74FCT2244ATSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2244A	Samples
CY74FCT2244CTQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2244C	Samples
CY74FCT2244CTSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2244C	Samples
CY74FCT2244CTSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2244C	Samples
CY74FCT2244CTSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2244C	Samples
CY74FCT2244TQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2244	Samples
CY74FCT2244TSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2244	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

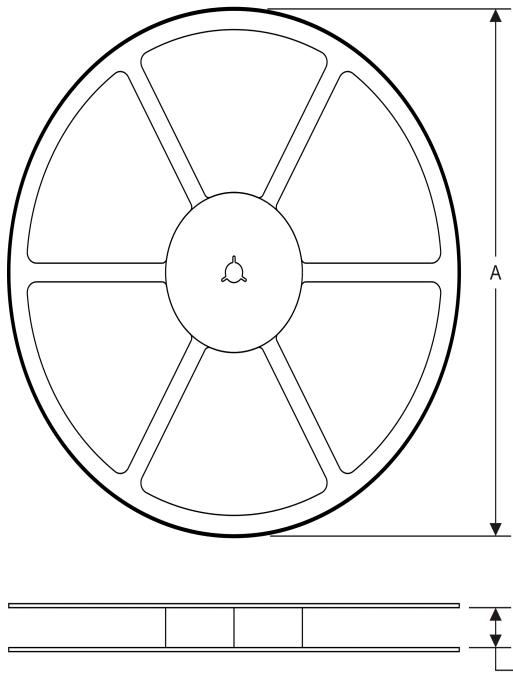
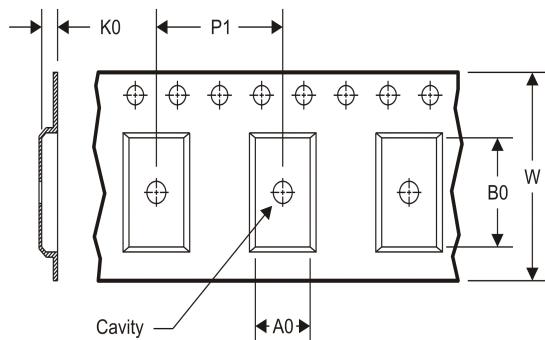
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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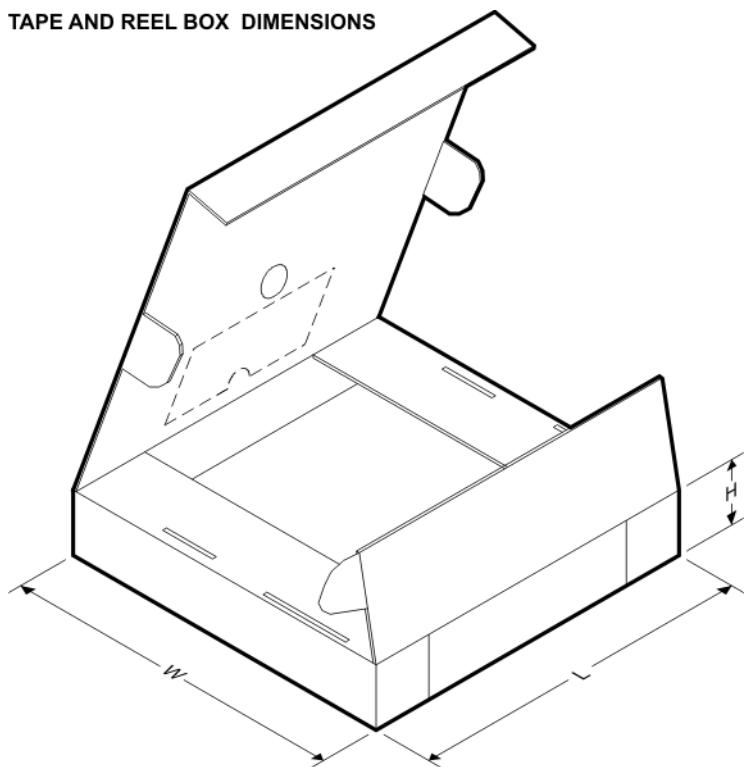
TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT2240CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2244ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2244CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2244CTSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CY74FCT2244TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

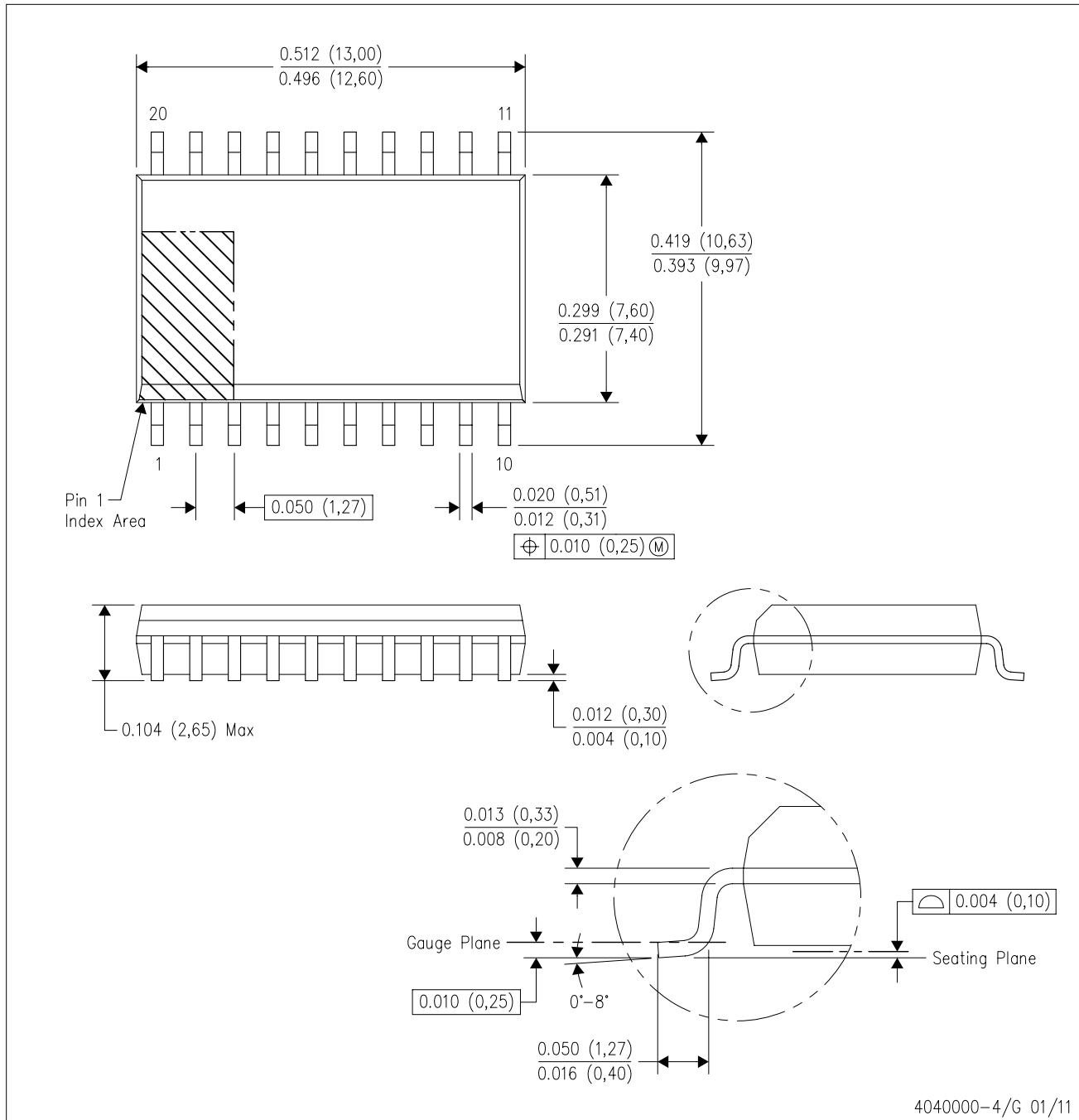
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT2240CTQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT2244ATQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT2244CTQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT2244CTSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT2244TQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

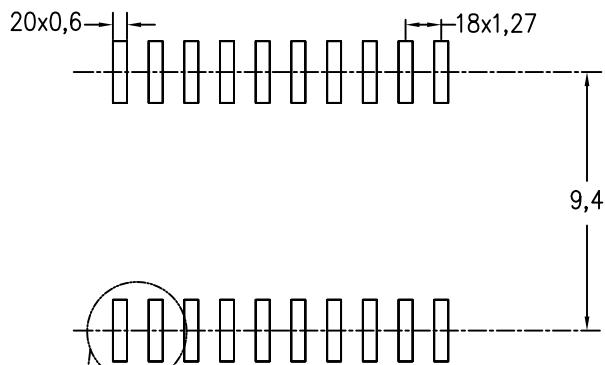
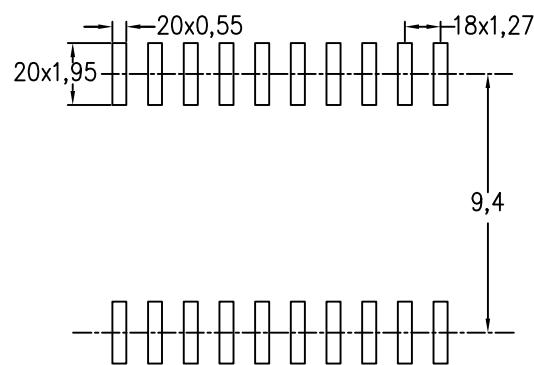


NOTES:

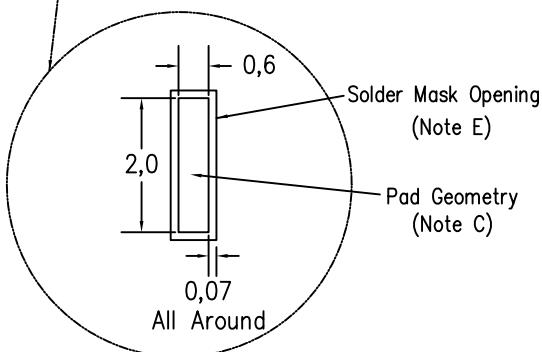
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)

Non Solder Mask Define Pad



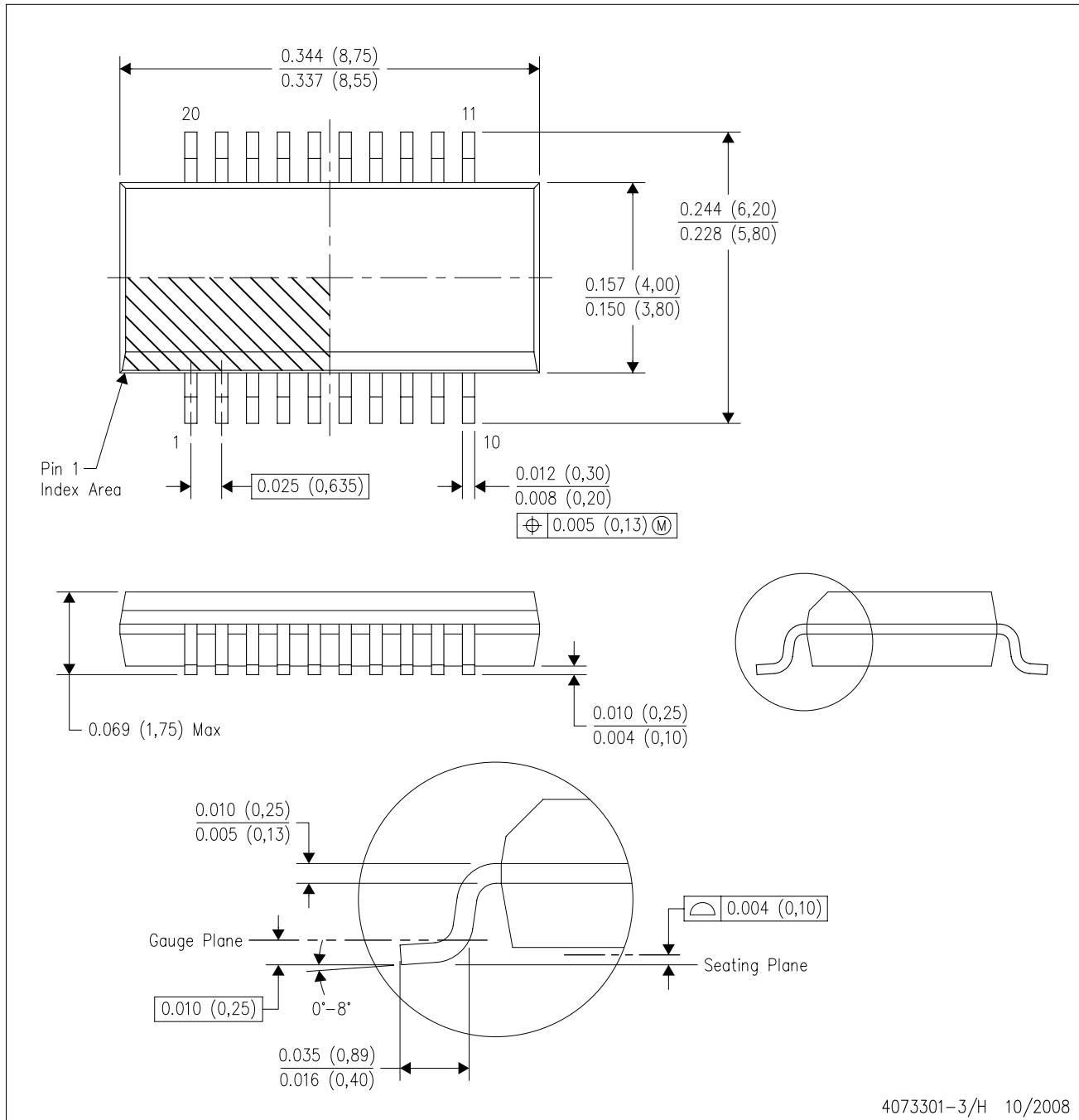
4209202-4/F 08/13

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DBQ (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



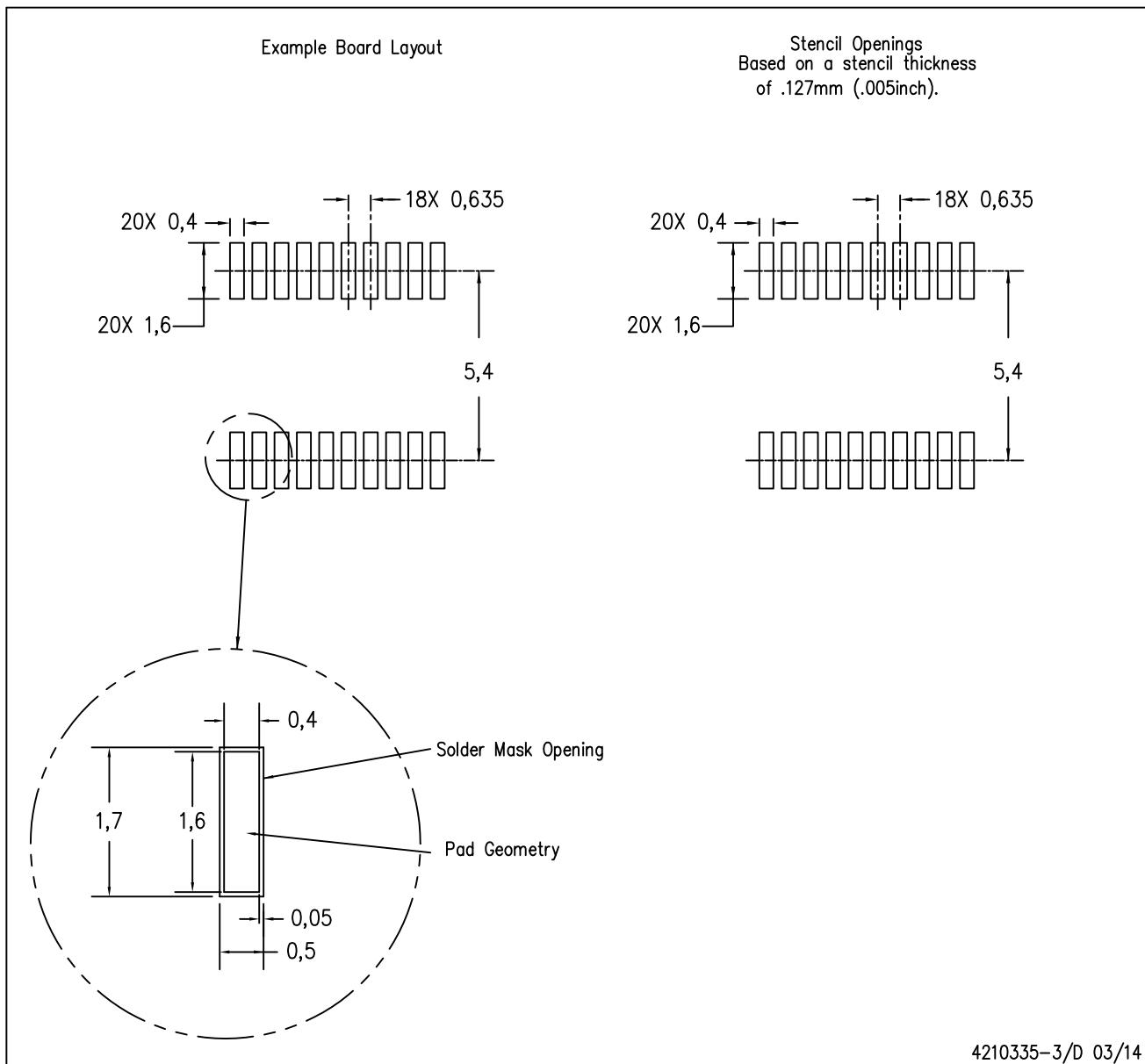
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
- Falls within JEDEC MO-137 variation AD.

LAND PATTERN DATA

DBQ (R-PDSO-G20)

PLASTIC SMALL OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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